

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>PO-CHENG SHIH</td> <td>10/14/2013</td> </tr> <tr> <td>HUI-CHUN YANG</td> <td>10/14/2013</td> </tr> <tr> <td>CHUNG-CHI KO</td> <td>10/14/2013</td> </tr> <tr> <td>KUANG-YUAN HSU</td> <td>10/14/2013</td> </tr> </tbody> </table>		Name	Execution Date	PO-CHENG SHIH	10/14/2013	HUI-CHUN YANG	10/14/2013	CHUNG-CHI KO	10/14/2013	KUANG-YUAN HSU	10/14/2013		
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>HSIN-CHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	HSIN-CHU SCIENCE PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
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Application Number:	14053727												
CORRESPONDENCE DATA													
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	TSMCP322US												
NAME OF SUBMITTER:	THOMAS G. ESCHWEILER												

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Signature:	/Thomas G. Eschweiler/
Date:	10/15/2013
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U.S. Patent Appln. No.

Docket No. TSMCP322US

Filing Date:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

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Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"HIGH UV CURING EFFICIENCY FOR LOW-K DIELECTRICS" for which:

a non-provisional application for United States Letters Patent:

U.S. Patent Appln. No.

Docket No.TSMCP322US

Filing Date:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by

PATENT**REEL: 031403 FRAME: 0818**

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ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2013. Oct. 14th
Date

✓ Po-Cheng Shih
Name 1st Inventor Po-Cheng Shih

TSMC Docket No. TSMC2013-0593

Docket No. TSMCP322US

U.S. Patent Appln. No.

Filing Date:

✓ 2013.10.14
Date

✓ Hui-Chun Yang
Name 2nd Inventor Hui-Chun Yang

PATENT

U.S. Patent Appln. No.

Filing Date:

✓ 2.15.10/14
Date

TSMC Docket No. TSMC2013-0593

Docket No. TSMCP322US

✓ chy-ch-hs
Name 3rd Inventor Chung-Chi Ko

PATENT

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Filing Date:

✓ 2013.10.14

Date

✓ Kuang-Yuan Hsu

Name 4th Inventor Kuang-Yuan Hsu